

**Product / Package Information**

Package	LFCSP
Body Size (mm)	5X5X0.75
Lead Count	32
Terminal Finish	Ni_Pd_Au
MS Number	MS012249C

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.38E-02	86.9	869100	39.55	395496
Thermosets	Epoxy & Phenol Resin	Proprietary	3.50E-03	12.8	127800	5.82	58157
Other inorganic materials	Carbon black	1333-86-4	8.48E-05	0.3	3100	0.14	1411
Subtotal			2.73 E-02	100.00	1000000	45.51	455064

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.90 E-02	97.50	975000	48.24	482434
Copper & its alloys	Iron	7439-89-6	6.99 E-04	2.35	23500	1.16	11628
Copper & its alloys	Zinc	7440-66-6	3.57 E-05	0.12	1200	0.06	594
Copper & its alloys	Phosphorus	7723-14-0	8.92 E-06	0.03	300	0.01	148
Subtotal			2.97 E-02	100.00	1000000	49.48	494804

**Internal/ External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.44 E-04	81.91	819149	0.41	4053
Precious metals	Palladium	7440-05-3	3.80 E-05	12.77	127660	0.06	632
Precious metals	Gold	7440-57-5	1.58 E-05	5.32	53191	0.03	263
Subtotal			2.97 E-04	100.0	1000000	0.49	4948

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	3.28 E-04	99.00	990000	0.55	5451
Precious metals	Palladium	7440-05-3	3.31 E-06	1.00	10000	0.01	55
Subtotal			3.31 E-04	100.0	1000000	0.55	5506

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.09 E-03	100.0	1000000	3.48	34800

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.26 E-04	77.00	770000	0.38	3756
Other organic materials	Acrylic resin	Proprietary	2.05 E-05	7.00	70000	0.03	341
Other organic materials	Acrylate	Proprietary	1.61 E-05	5.50	55000	0.03	268
Other organic materials	Polybutadiene derivative	Proprietary	1.32 E-05	4.50	45000	0.02	220
Other organic materials	Epoxy resin	Proprietary	7.33 E-06	2.50	25000	0.01	122
Other organic materials	Butadiene Copolymer	Proprietary	4.40 E-06	1.50	15000	0.007	73
Others	Additive	Proprietary	4.40 E-06	1.50	15000	0.007	73
Others	Peroxide	Proprietary	1.47 E-06	0.50	5000	0.002	24
Subtotal			2.93 E-04	100.00	1000000	0.49	4878

<b>Package Totals</b>			<b>Weight (g)</b> 6.01 E-02			<b>Percentage (%)</b> 100	<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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